Features

- Split Gate Trench MOSFET Technology
- Low $R_{DS(on)}$ & FOM
- Low Crss
- Extremely Low Switching Loss
- Excellent Stability and Uniformity
- Halogen Free. “Green” Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Moisture Sensitivity Level 1

P-CHANNEL MOSFET

Maximum Ratings

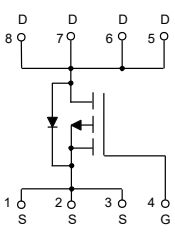
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance:50°C/W Junction to Ambient(Steady-State)(2)
- Thermal Resistance:1.7°C/W Junction to Case(Steady-State)

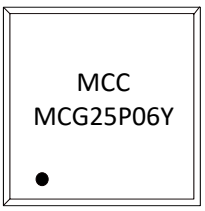
Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	-60	V
Gate-Source Volltage		V_{GS}	±20	V
Continuous Drain Current	T_C=25°C	I_D	-25	A
	T_C=100°C		-15.8	
Pulsed Drain Current(3)		I_{DM}	-75	A
Total Power Dissipation(4)		P_D	73.5	W
Single Pulsed Avalanche Energy(5)		E_{AS}	81	mJ

Note:

1. Halogen free "Green” products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ t≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. VDD=-50V,RG=25Ω， L=0.5mH,IAS=-18A

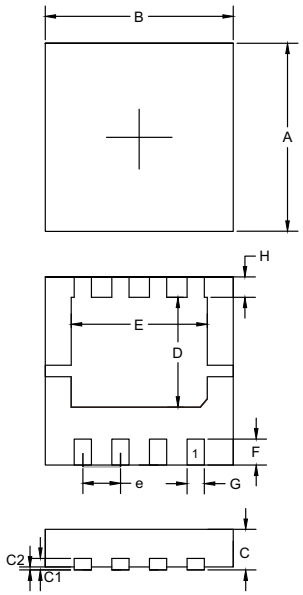
Internal Structure and Marking Code





pin1

DFN3333



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.126	0.130	3.20	3.30	
B	0.126	0.130	3.20	3.30	
C	0.030	0.033	0.75	0.85	
C1	0.007	0.009	0.18	0.22	
C2	---	0.002	---	0.05	
D	0.071	0.079	1.80	2.00	
E	0.087	0.098	2.20	2.50	
F	0.016	0.020	0.40	0.50	
G	0.010	0.014	0.25	0.35	
H	0.012	0.016	0.30	0.40	
e	0.024	0.028	0.60	0.70	

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D=-250μA	-60			V
Gate-Source Leakage Current	I_{GSS}	V_{DS}=0V, V_{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=-60V, V_{GS}=0V			-1	μA
Gate-Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-250μA	-1.5	-2.1	-2.7	V
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=-10V, I_D=-20A		38	50	mΩ
		V_{GS}=-4.5V, I_D=-10A		48	65	
Gate Resistance	R_g	F=1 MHz, Open drain		12		Ω
Diode Characteristics						
Continuous Body Diode Current	I_S				-25	A
Diode Forward Voltage	V_{SD}	V_{GS}=0V, I_S=-20A		-0.95	-1.3	V
Reverse Recovery Time	t_{rr}	I_F=-20A, dI_F/dt=100A/μs		28.3		ns
Reverse Recovery Charge	Q_{rr}			20.2		nC
Dynamic Characteristics						
Input Capacitance	C_{iss}	V_{DS}=-30V,V_{GS}=0V,f=1MHz		1024		pF
Output Capacitance	C_{oss}			386		
Reverse Transfer Capacitance	C_{rss}			22		
Total Gate Charge	Q_g	V_{DS}=-30V,V_{GS}=-10V,I_D=-20A		17.4		nC
Gate-Source Charge	Q_{gs}			3.83		
Gate-Drain Charge	Q_{gd}			2.94		
Turn-On Delay Time	$t_{d(on)}$	V_{DD}=-30V, V_{GS}=-10V , R_{GEN}=6Ω		7.9		ns
Turn-On Rise Time	t_r			4.63		
Turn-Off Delay Time	$t_{d(off)}$			42.4		
Turn-Off Fall Time	t_f			15.7		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

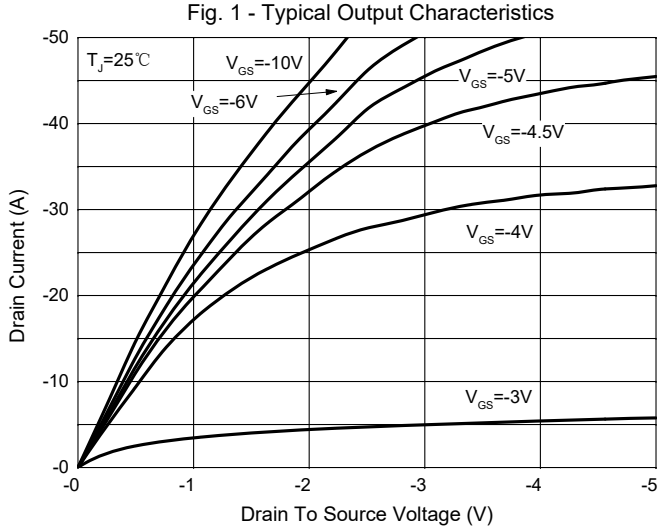


Fig. 2 - Transfer Characteristics

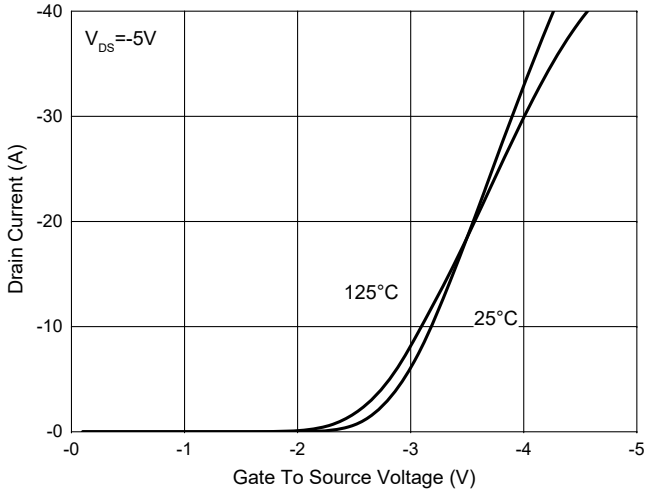


Fig. 3 - $R_{DS(ON)}$—I_D

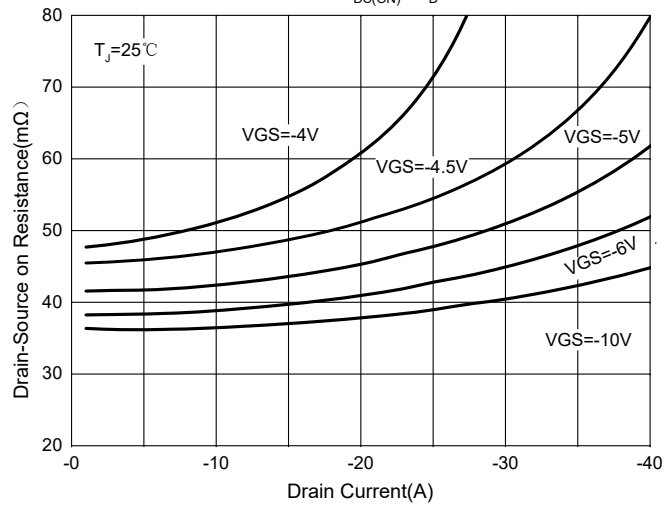


Fig.4-NormalizedOnResistanceCharacteristics

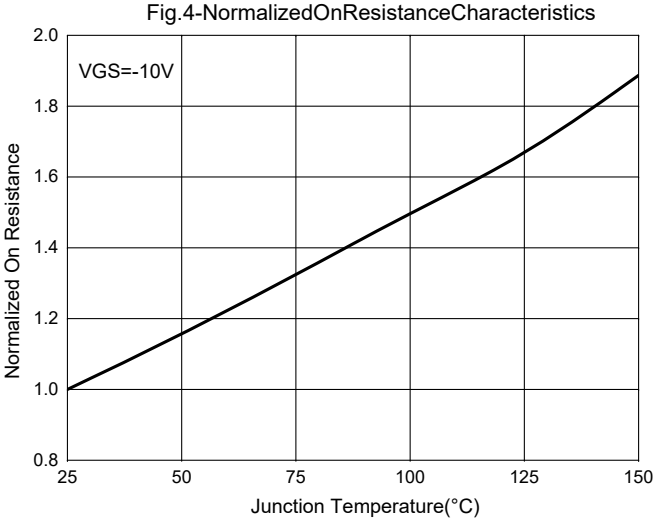


Fig. 5 - Capacitance Characteristics

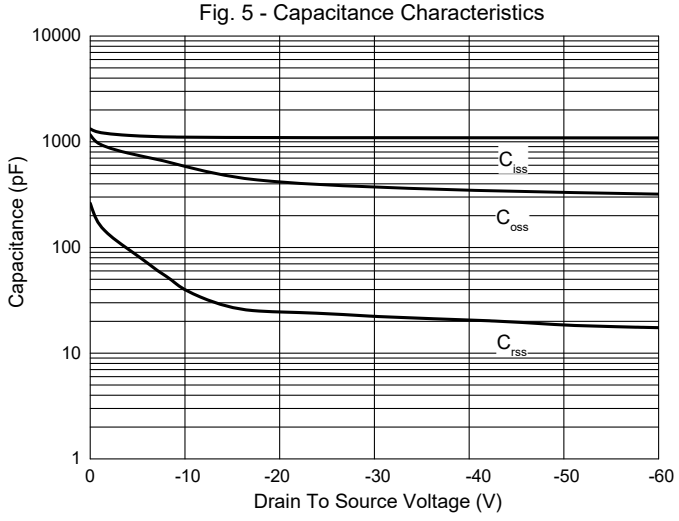
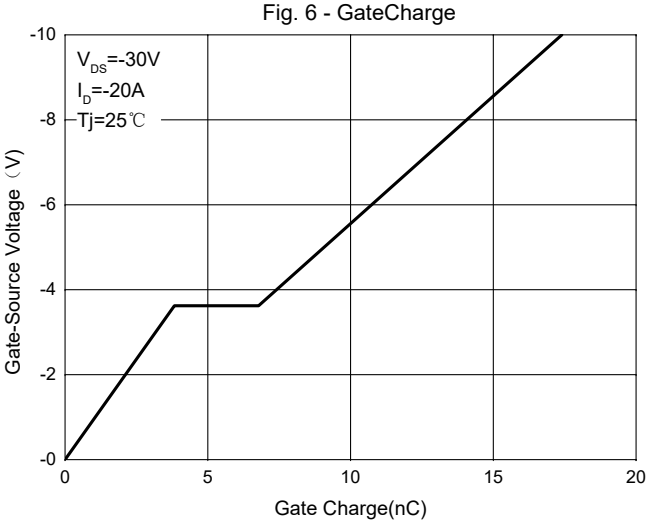


Fig. 6 - GateCharge



Curve Characteristics

Fig. 7 - $R_{DS(ON)}$—V_{GS}

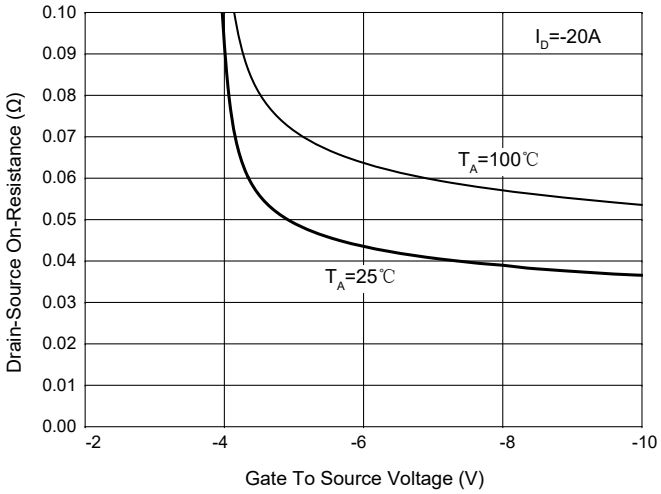


Fig. 8 - V_{TH}—T_J

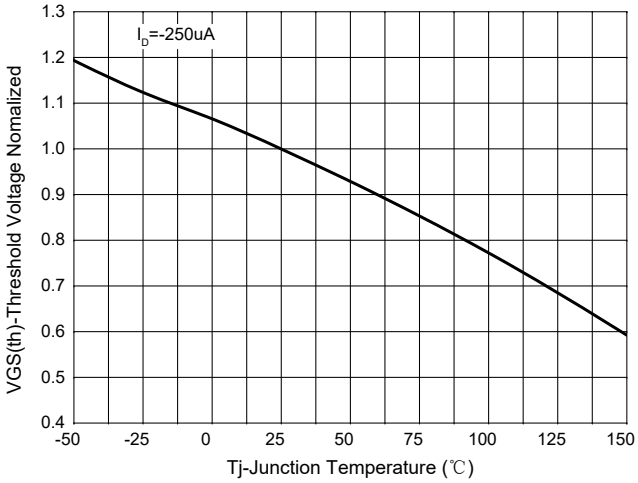


Fig. 9 - I_S—V_{SD}

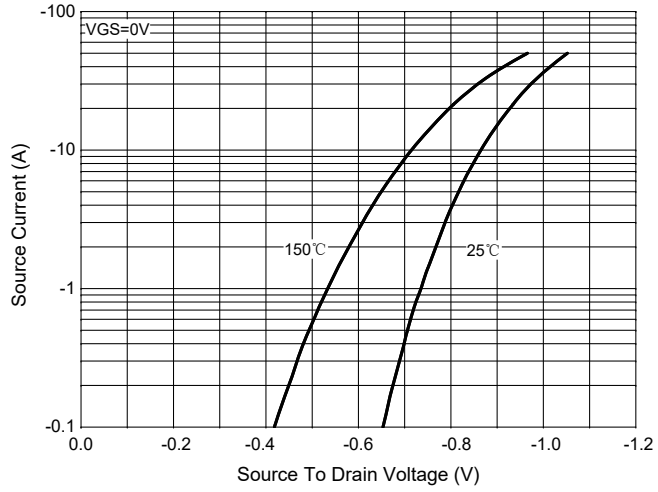


Fig. 10 - Current dissipation

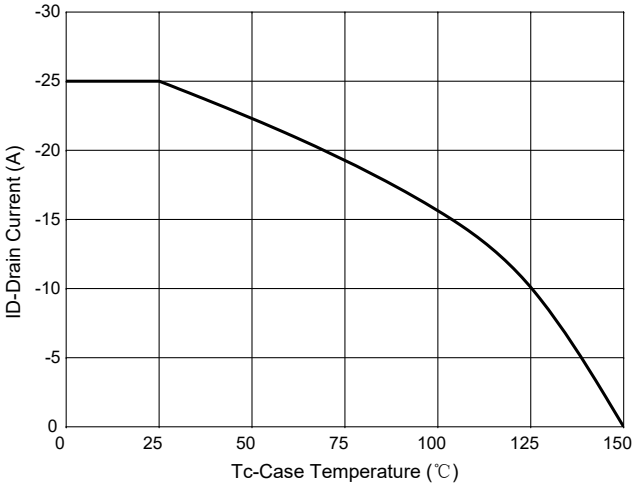
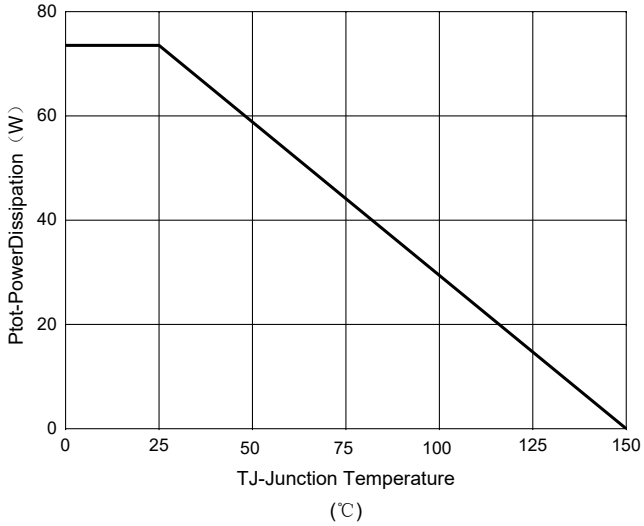


Fig.11-PowerDissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

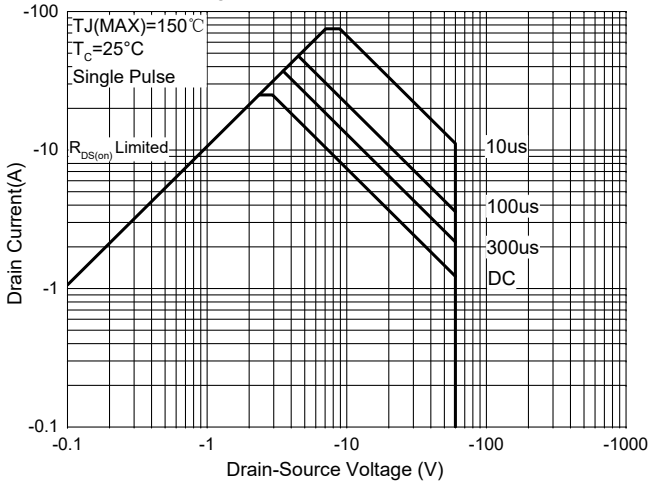
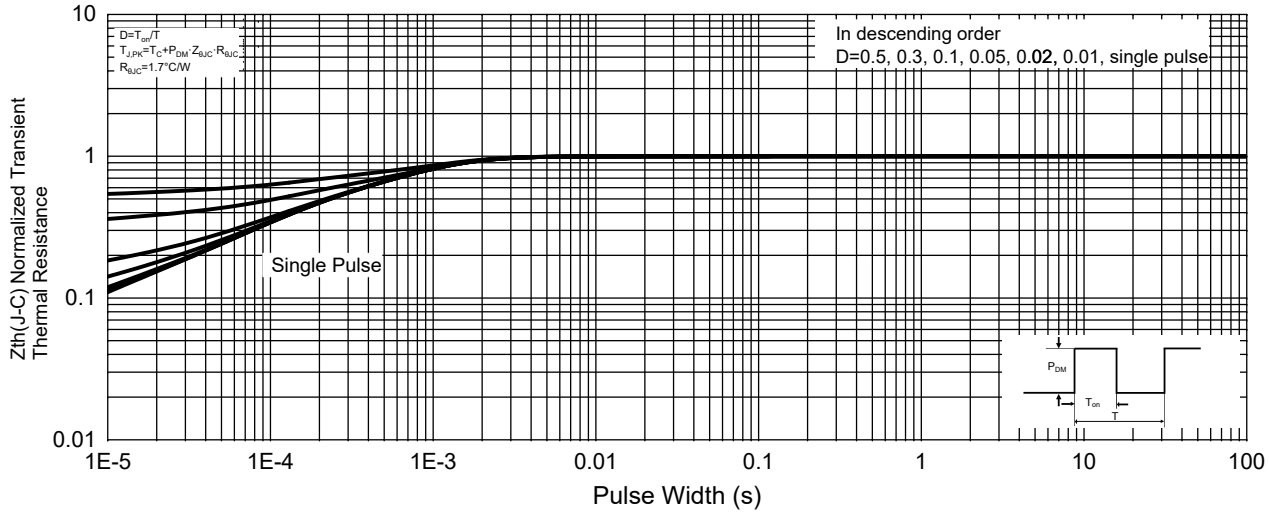


Fig. 13 -Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
MCG25P06Y-TP	Tape&Reel: 5Kpcs/Reel